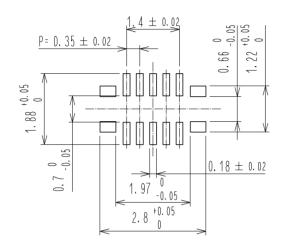
FORM HC0011-5-8 1

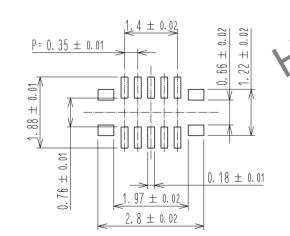
© RECOMMENDED REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE.

◆ RECOMMENDED PCB LAYOUT



♦ RECOMMENDED METAL MASK DIMENSIONS

METAL MASK THICKNESS : 100 \(\mu \) m



MAX 250 ℃ 250 180 ----180 ----180 ----RENVINGE
RENVINGE
10040
10040
10040 2200 220 180° TIME (SECONDS) 90~120 SECONDS MAX 60 SECONDS PRE-HEATING TIME SOLDERING TIME

NUMBER OF REFLOW CYCLES: 2 CYCLES MAX.

1) REFLOW TIME DURATION ABOVE 220°C, 60 SEC. MAX. (PEAK TEMPERATURE: 250℃ MAX)

2) PRE-HEAT TIME PRE-HEAT TEMPERATURE(MIN): 150℃ PRE-HEAT TEMPERATURE(MAX): 180℃ PRE-HEAT TIME: 90-120 sec.

6>THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE. ADDISIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE, THEREFORE, A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.

PART NO. BM15FRO. 8-10DP-0. 35V(51)	DRA'N	EDC3-3	55886-01
			10DP-0.35V(51)
		CL673-122	$6-8-51$ \triangle 2/3

